



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model

[List multiple models if applicable.]

HP Compaq dx7500 Small Form Factor Business PC

Name / Model #2

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3 (1 sys bd, 2 P/S PCAs)
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		7 (5 P/S capacitors, 2 P/S condensers)
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

1.3 Markings for plastic parts greater than 25 grams

Plastic Part Name	Plastic Part Description	Weight (grams)	ISO 11469:2000 Plastic Part Mark	Optional: Photo
Santa Anna SFF Main Bezel	Main front bezel piece	72	>ABS<	
Santa Anna SFF Bezel Frame	Front bezel frame	54	>ABS<	
SFF CPU Cooler Fan Duct	Duct for CPU fan	30	>PC+ABS FR(40)<	

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Phillips screwdriver	
Description #2 Dikes	
Description #3 Torx screwdriver	T-15

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. To remove the access panel (see Figure 1):
 - a. Disconnect the power cord from the power outlet and the computer (1), and disconnect any external devices.
 - b. Remove the two screws that secure the access panel to the computer chassis (2).
 - c. Slide the access panel back about 1.3 cm (1/2 inch), then lift it away from and off the unit (3).
2. Remove the front bezel, pull up on each of the three tabs on the top of the bezel (1) to release them, then rotate the bezel down and off the chassis (2). (see Figure 2):
 - a. Release the three front bezel latches on the top side of the bezel.
 - b. Rotate the and remove the bezel.
3. Remove or cut all expansion cards, cables, and any other devices from the system board.
4. To remove the heatsink from the system board (see Figure 3):
 - a. Loosen the four captive screws that secure the heatsink to the system board.
 - b. Lift the heatsink from atop the processor and set it aside.
5. To remove the system board (see Figure 4):
 - a. Remove the 8 screws that secure the system board to the chassis.
 - b. Lift the system board and slide it toward the front of the chassis and up to remove it.

NOTE: System board appearance may vary.
6. To remove the battery:

Locate the battery and battery holder on the system board. Depending on the type of battery holder on the system board, complete the following instructions to remove the battery.

TYPE 1 BATTERY HOLDER (see Figure 5):
Lift the battery out of the holder.

TYPE 2 BATTERY HOLDER (see Figure 6):
To release the battery from its holder, squeeze the metal clamp that extends above one edge of the battery. When the battery pops up, lift it out.

TYPE 3 BATTERY HOLDER (see Figure 7):
Pull back on the clip that holds the battery in place, and then remove the battery.
7. To remove the power supply:
 - a. Remove the three Phillips screws that secure the power supply to the chassis (see Figure 8).
 - b. On the inside of the chassis, remove the Phillips screw that secures the power supply to the chassis floor (see Figure 9).
 - c. Slide the power supply toward the front of the computer, rotate toward the fan so the power supply clears the lip on the top of the chassis, and then lift the power supply out of the chassis.

Disassemble and remove required power supply components:

 - a. Using dikes, cut the plastic clamp that secures the wires to the power supply cover (see Figure 10).

b. Using a Phillips screwdriver, remove the four screws that secure the cover to the power supply chassis (see Figures 11 & 12).

NOTE: You do not need to remove the screws from the fan guard or the power connector.

c. Lift the cover off the power supply.

d. Disconnect two control cables from the PSU PCA (see Figure 13)

e. Using dikes, cut all cables connecting the PCA to the power supply.

f. Remove the three screws that secure the power supply PCA to the chassis (see Figure 14).

g. Remove the power supply PCA from the power supply chassis.

h. Cut the capacitors as shown in Figure 15.

i. Cut the small PCA from the large PCA as shown in Figure 16.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

FIGURE 1: Removing the access panel.

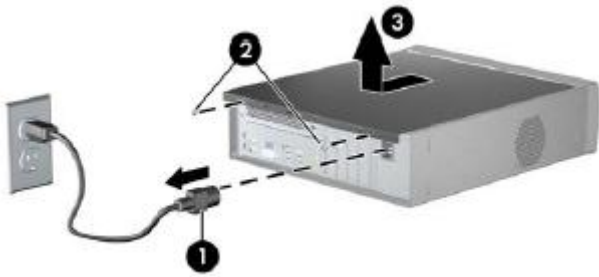


FIGURE 2: Removing the front bezel



FIGURE 3: Heatsink screws to loosen



FIGURE 4: System board screw locations



FIGURE 5: Type 1 battery holder

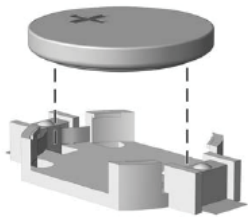


FIGURE 6: Type 2 battery holder

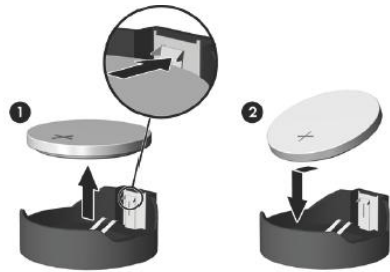


FIGURE 7: Type 3 battery holder

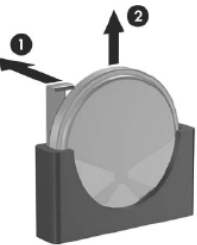


FIGURE 8: Power supply screw locations



FIGURE 9: Power supply inner screw location



FIGURE 10: Power supply cover plastic cable clamp



FIGURE 11: POWER SUPPLY : Cover screw locations



FIGURE 12: POWER SUPPLY: Cover screw locations

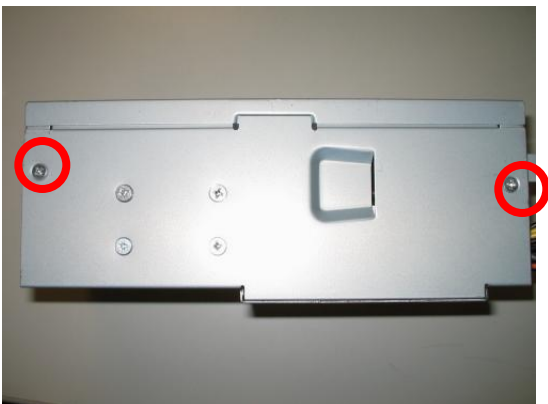


FIGURE 13: POWER SUPPLY: Control cables to disconnect

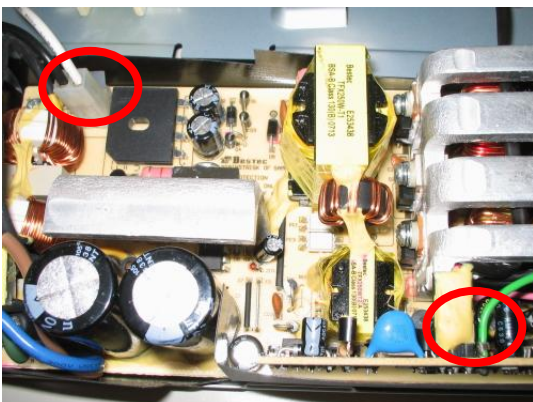


FIGURE 14: POWER SUPPLY : PCA screw locations

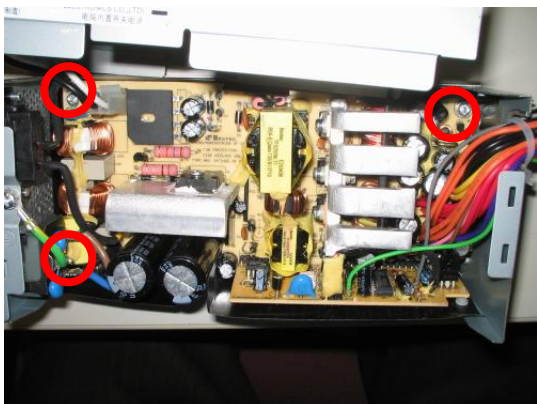


FIGURE 15: POWER SUPPLY: Capacitors to cut

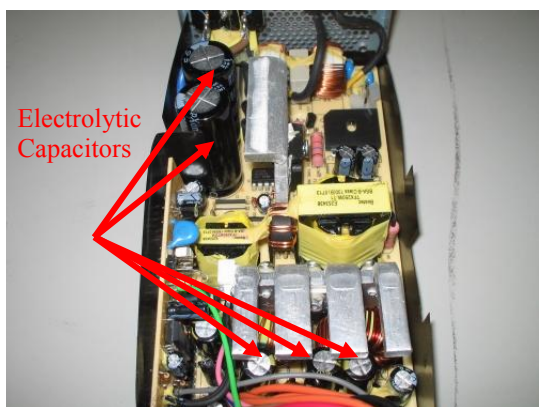


FIGURE 16: POWER SUPPLY: Small PCA to remove

